### T-1 (3mm) RIGHT ANGLE LED INDICATOR

Part Number: WP934EW/SRD Super Bright Red

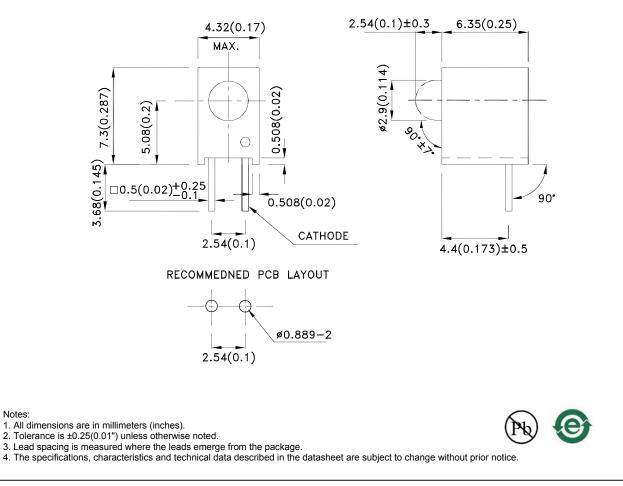
#### Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

### Package Dimensions



SPEC NO: DSAF1857 APPROVED: WYNEC REV NO: V.5A CHECKED: Allen Liu DATE: MAR/28/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102013069

#### **Selection Guide** lv (mcd) [2] Viewing @ 20mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. 150 400 40° WP934EW/SRD Super Bright Red (GaAlAs) Red Diffused \*100 \*50

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	655		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA
С	Capacitance	Super Bright Red	45		pF	V⊧=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V

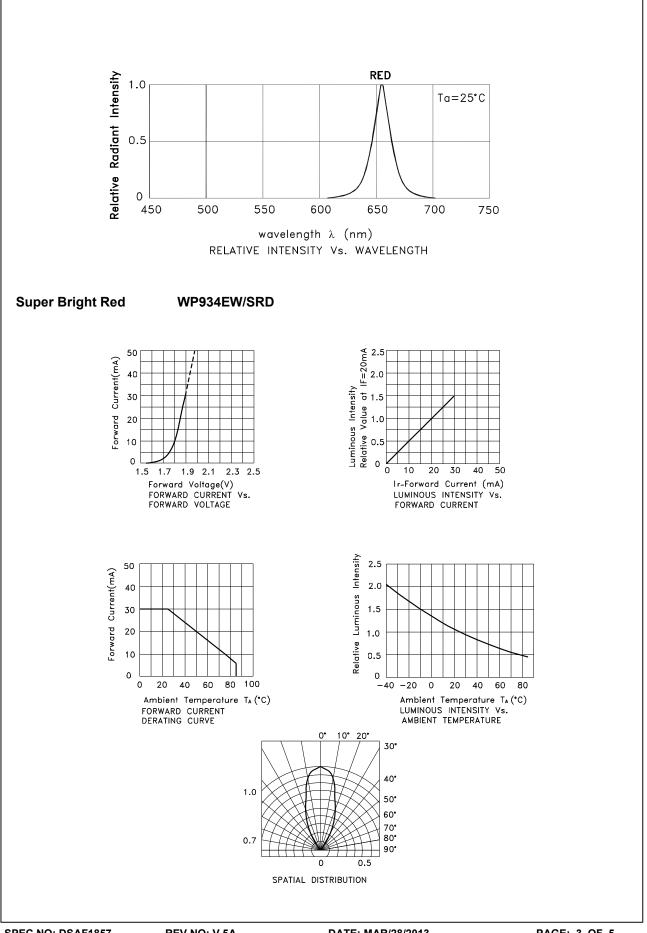
Notes: 1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

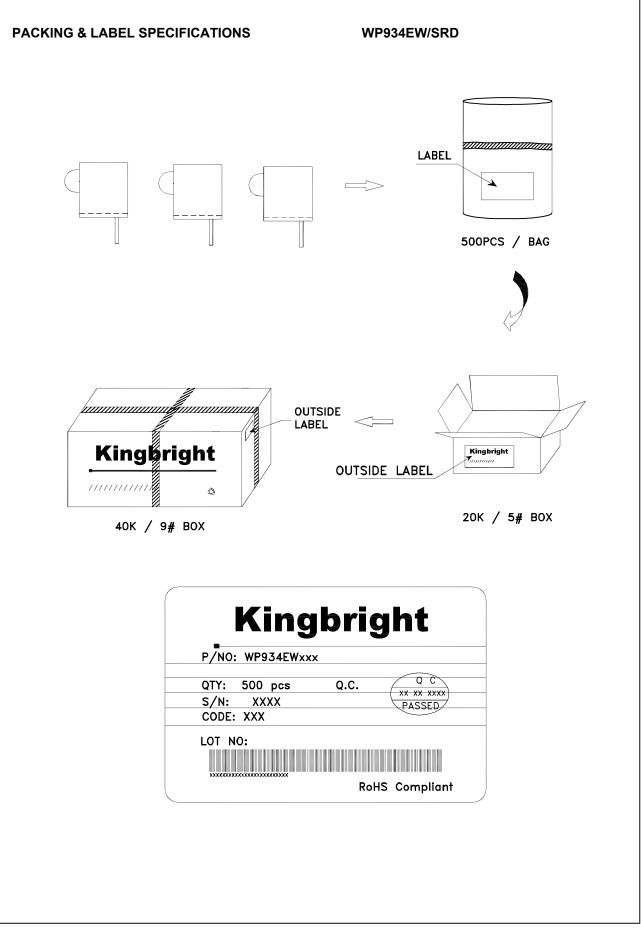
### Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Red			
Power dissipation	75			
DC Forward Current	30	mA		
Peak Forward Current [1]	155	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

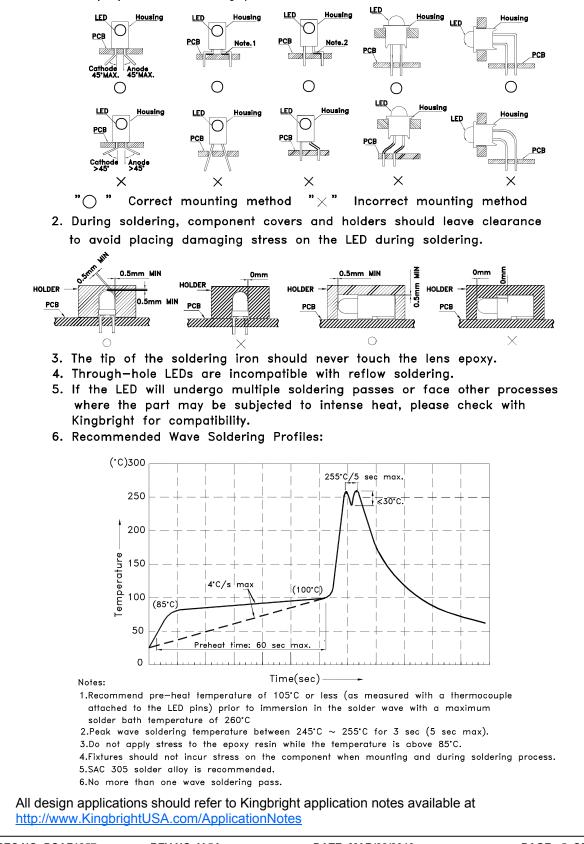
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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